(-15541,14017)

JEFFERSON LAB
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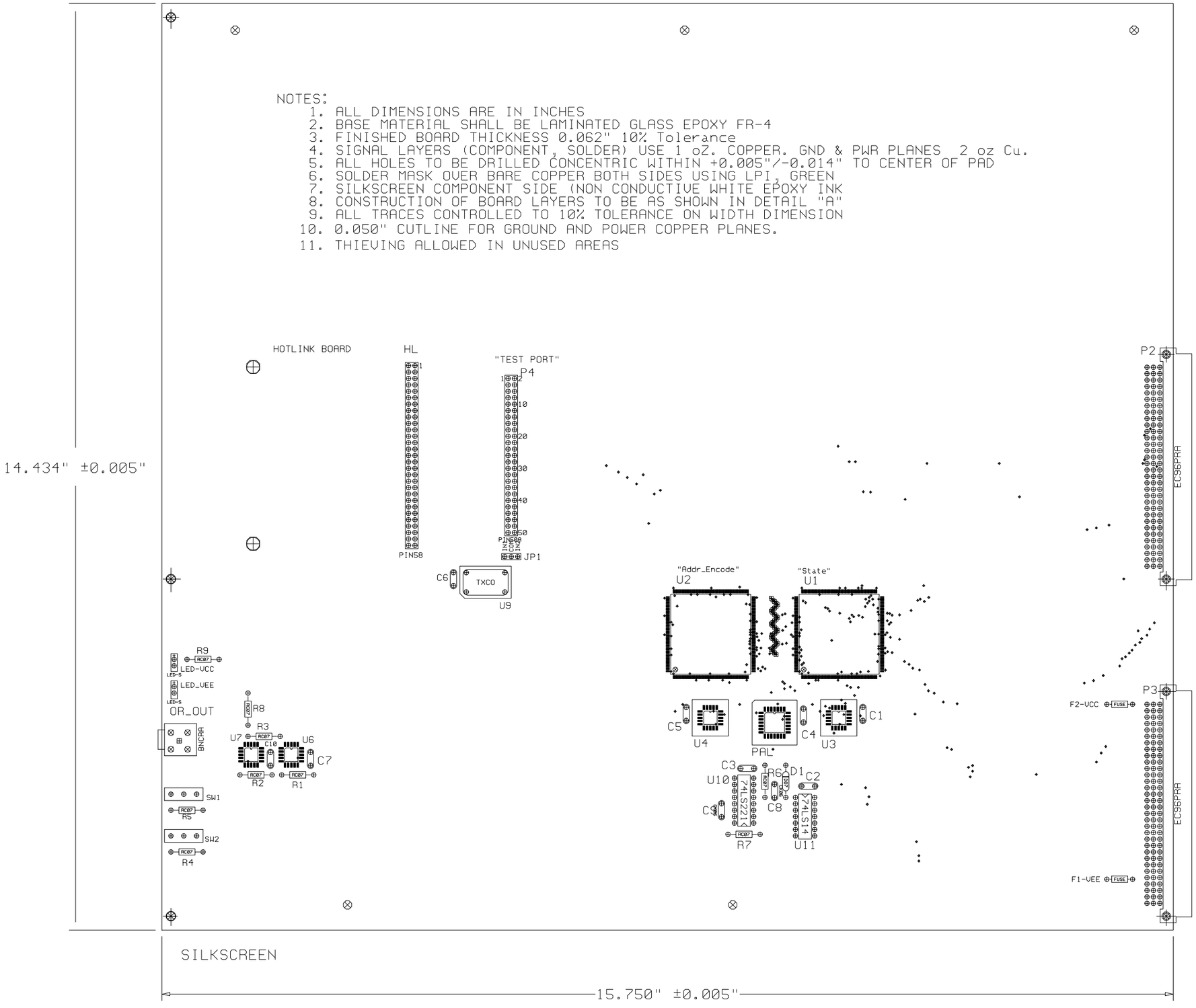
JOB NAME: SEGMENT COLLECTOR

NOTES:
1. ALL DIMENSIONS ARE IN INCHES
2. BASE MATERIAL SHALL BE LAMINATED GLASS EPOXY FR-4
3. FINISHED BOARD THICKNESS 0.062" 10% Tolerance
4. SIGNAL LAYERS (COMPONENT, SOLDER) USE 1 oZ. COPPER. GND & PWR PLANES 2 oz Cu.
5. ALL HOLES TO BE DRILLED CONCENTRIC WITHIN +0.005"/-0.014" TO CENTER OF PAD
6. SOLDER MASK OVER BARE COPPER BOTH SIDES USING LPI, GREEN
7. SILKSCREEN COMPONENT SIDE (NON CONDUCTIVE WHITE EPOXY INK
8. CONSTRUCTION OF BOARD LAYERS TO BE AS SHOWN IN DETAIL "A"
9. ALL TRACES CONTROLLED TO 10% TOLERANCE ON WIDTH DIMENSION
10. 0.050" CUTLINE FOR GROUND AND POWER COPPER PLANES.
11. THIEVING ALLOWED IN UNUSED AREAS



SYMBOL	HOLE SIZE AFTER PLATING	COUNT
◇	0.015" +/-0.005"	303
⊕	0.038" +/- 0.0035"	391
⊞	0.040" +/- 0.005"	1
⊗	0.060" +/- 0.005"	4
⊠	0.105" +/- 0.005"	12
⯐	0.150" +/- 0.005"	2
	TOTAL	713

No.	LAYER	DIELECTRIC	Cu WEIGHT
1.	COMPONENT		1 oZ.
		0.010"	
2.	+5VDC/-5.2VDC		2 oZ.
		0.018"	
5.	GND		2 oZ.
		0.010"	
6.	SOLDER		1 oz.

TOTAL THICKNESS 0.062" +/- 0.007"

Note: Dielectric values are left up to the manufacturer provided the board thickness is as specified.

DETAIL "A"